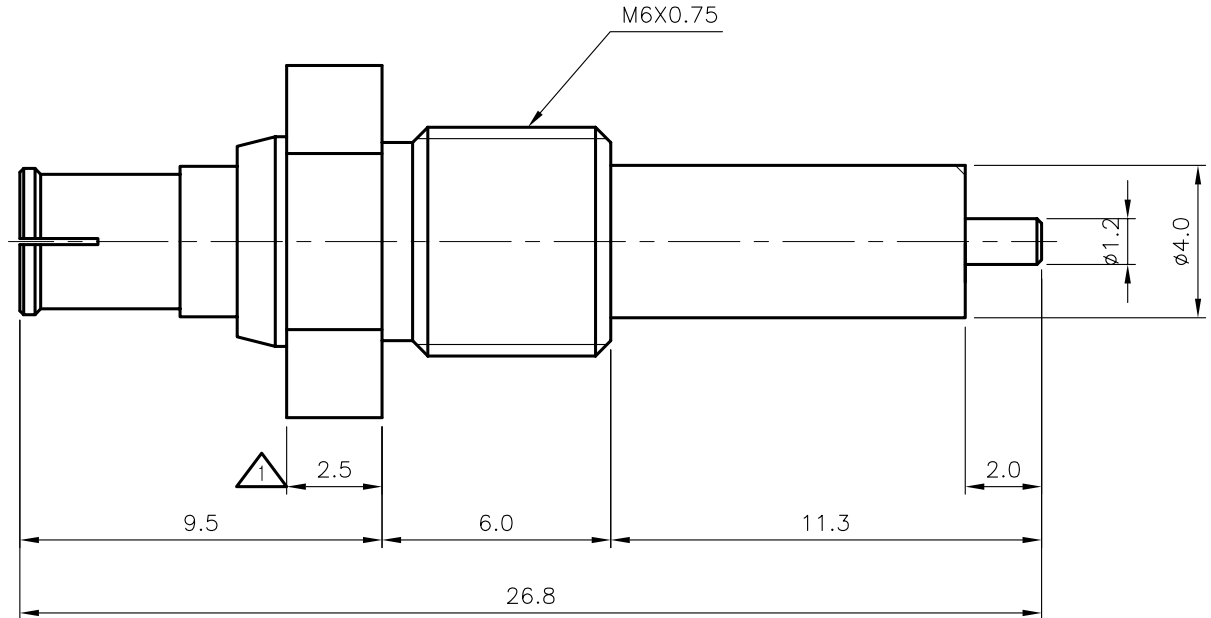
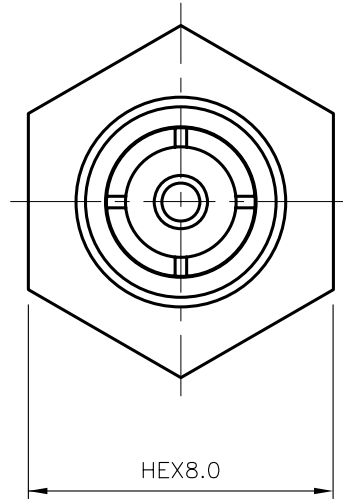
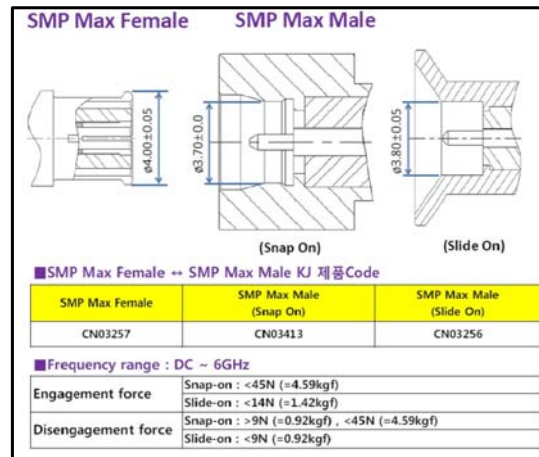


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2015.01.20.
1	플렌지 1.7에서 2.5로 길이 변경	H.J.LEE	I.C.KIM	



■ Mating 검사 진행



3	INSULATOR	1	TEFLON		DIN02532-N/1
2	CONTACT	1	BeCu	Silver Plate	DCT03171-5/2
1	BODY	1	BeCu	SUCO Plate	DBD03670-5/4
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2015. 01. 20.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL	-	CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMP MAX SOLDER END JB (F/F)
		DRAWN BY	H.J.LEE	
FINISH	-	SCALE	5/1	A4 DWG NO. CN03257-7/3 REVISION I R SHEET 1 of 1
		UNIT	mm	